



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:
Boyd et al
Serial No. 10/606,022

Examiner: PERRIN, J.
Art Unit: 1746
Atty Docket No. LAM2P425

Filed: June 24, 2003

Date: February 6, 2007

For: SYSTEM AND METHOD
FOR INTEGRATING IN-SITU
METROLOGY WITHIN A
WAFER PROCESS

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CERTIFICATE OF MAILING

I hereby certify that this paper (along with any paper referred to as being attached or enclosed) is being deposited with the United States Postal Service as First Class Mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on February 6, 2007.

Signed: _____

George B. Leavell

AMENDMENT AND RESPONSE TO OFFICE ACTION

Commissioner for Patents
Alexandria, VA 22313-1450

In response to the Office Action mailed December 14, 2006, please amend the above-referenced application as follows:

Amendments to the Specification begin on page 2 of this paper.

A complete listing of claims with their current status begins on page 3 of this paper.

Remarks begin on page 7 of this paper.